

METHOD AND SYSTEM FOR INTEGRATED CIRCUIT PACKAGING

ABSTRACT OF THE DISCLOSURE

According to one embodiment of the invention, a method of packaging integrated circuits includes disposing an integrated circuit chip outwardly from a first surface of a substrate, positioning the integrated circuit chip and the substrate between
5 a first mold press die and a second mold press die, and engaging the first mold press die with the second mold press die such that the integrated circuit chip is disposed within a cavity formed by the engagement of the first mold press die with the second mold press die. The cavity includes a pre-warped configuration. The method further includes encapsulating the integrated circuit chip with a mold compound such that the
10 mold compound takes on the pre-warped configuration of the cavity, removing the encapsulated integrated circuit chip from the cavity, and curing the mold compound. The curing transforms the mold compound from the pre-warped configuration to a predefined configuration.